

RHRG7570, RHRG7580, RHRG7590, RHRG75100

January 2002

75A, 700V - 1000V Hyperfast Diode

Features

- Hyperfast with Soft Recovery
 Operating Temperature+175°C
- Avalanche Energy Rated
- Planar Construction

Applications

- Switching Power Supplies
- Power Switching Circuits
- General Purpose

Description

RHRG7570, RHRG7580, RHRG7590 and RHRG75100 (TA49068) are hyperfast diodes with soft recovery characteristics ($t_{\rm RR}$ < 85ns). They have half the recovery time of ultrafast diodes and are silicon nitride passivated ionimplanted epitaxial planar construction.

These devices are intended for use as freewheeling/clamping diodes and rectifiers in a variety of switching power supplies and other power switching applications. Their low stored charge and hyperfast soft recovery minimize ringing and electrical noise in many power switching circuits reducing power loss in the switching transistors.

These devices are supplied in the 2 lead JEDEC style TO-247 plastic package.

Due to space limitations, the brand on the RHRG75100 is abbreviated to HRG75100.

To order this part use the full part number, i.e. RHRG75100.

Package JEDEC STYLE TO-247 TOP VIEW ANODE CATHODE (BOTTOM SIDE METAL) CATHODE

Symbol



Absolute Maximum Ratings (T_C = +25°C), Unless Otherwise Specified

	RHRG7570	RHRG7580	RHRG7590	RHRG75100	UNITS	
Peak Repetitive Reverse VoltageV _{RRM}	700	800	900	1000	V	
Working Peak Reverse VoltageV _{RWM}	700	800	900	1000	V	
DC Blocking VoltageV _R	700	800	900	1000	V	
Average Rectified Forward Currentl _{F(AV)} $(T_C = +52^{\circ}C)$	75	75	75	75	Α	
Repetitive Peak Surge CurrentI _{FSM} (Square Wave, 20kHz)	150	150	150	150	Α	
Nonrepetitive Peak Surge Currentl _{FSM} (Halfwave, 1 phase, 60Hz)	750	750	750	750	Α	
Maximum Power DissipationP _D	190	190	190	190	W	
Avalanche Energy (L = 40mH) (See Figures 10 and 11)E _{AVL}	50	50	50	50	mj	
Operating and Storage Temperature T_{STG} , T_{J}	-65 to +175	-65 to +175	-65 to +175	-65 to +175	°C	

Specifications RHRG7570, RHRG7580, RHRG7590, RHRG75100

Electrical Specifications $T_C = +25^{\circ}C$, Unless Otherwise Specified

		RHRG7570		RHRG7580			RHRG7590			RHRG75100				
SYMBOL	TEST CONDITION	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	UNITS
V _F	$I_F = 75A, T_C = +25^{\circ}C$	-	-	3.0	-	-	3.0	-	-	3.0	-	-	3.0	V
	$I_F = 75A, T_C = +150^{\circ}C$	-	-	2.5	-	-	2.5	-	-	2.5	-	-	2.5	V
I _R	$V_R = 700V, T_C = +25^{\circ}C$	-	-	50	-	-	-	-	-	-	-	-	-	μΑ
	$V_R = 800V, T_C = +25^{\circ}C$	-	-	-	-	-	50	-	-	-	-	-	-	μΑ
	$V_R = 900V, T_C = +25^{\circ}C$							-	-	50				μΑ
	$V_R = 1000V, T_C = +25^{\circ}C$	-	-	-	-	-	-	-	-	-	-	-	50	μΑ
I _R	$V_R = 700V, T_C = +150^{\circ}C$	-	-	2.0	-	-	-	-	-	-	-	-	-	mA
	$V_R = 800V, T_C = +150^{\circ}C$	-	-	-	-	-	2.0	-	-	-	-	-	-	mA
	$V_R = 900V, T_C = +150^{\circ}C$							-	-	2.0				mA
	V _R = 1000V, T _C = +150°C	-	-	-	-	-	-	-	-	-	-	-	2.0	mA
t _{RR}	$I_F = 1A$, $dI_F/dt = 100A/\mu s$	-	-	85	-	-	85	-	-	85	-	-	85	ns
	I _F = 75A, dI _F /dt = 100A/ μs	-	-	100	-	-	100	-	-	100	-	-	100	ns
t _A	$I_F = 75A$, $dI_F/dt = 100A/$ µs	-	55	-	-	55	-	-	55	-	-	55	-	ns
t _B	$I_F = 75A$, $dI_F/dt = 100A/$ µs	-	40	-	-	40	-	-	40	-	-	40	-	ns
Q _{RR}	$I_F = 75A$, $dI_F/dt = 100A/$ µs	-	240	-	-	240	-	-	240	-	-	240	-	nC
СЈ	$V_R = 10V, I_F = 0A$	-	220	-	-	220	-		220		-	220	-	pF
$R_{\theta JC}$		-	-	0.8	-	-	0.8			0.8	-	-	0.8	°C/W

DEFINITIONS

 V_F = Instantaneous Forward Voltage (pw = 300 μ s, D = 2%)

 I_R = Instantaneous Reverse Current

 t_{RR} = Reverse Recovery Time (Figure 2), Summation of t_{A} + t_{B}

 t_A = Time to Reach Peak Reverse Current (See Figure 2).

 t_B = Time from Peak I_{RM} to Projected Zero Crossing of I_{RM} Based on a Straight Line from Peak I_{RM} Through 25% of I_{RM} (See Figure 2)

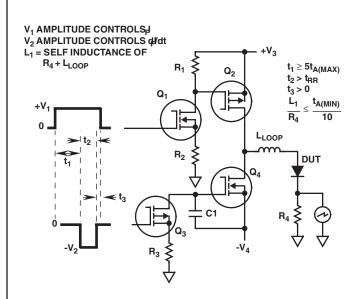
Q_{RR} = Reverse Recovery Charge

C_J = Junction Capacitance

 $R_{\theta JC}$ = Thermal Resistance Junction to Case

pw = Pulse Width

D = Duty Cycle



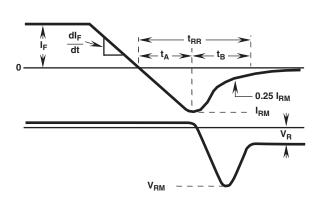
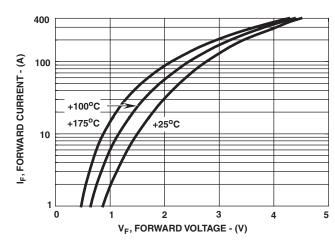


FIGURE 1. t_{RR} TEST CIRCUIT

FIGURE 2. t_{RR} WAVEFORMS AND DEFINITIONS

RHRG7570, RHRG7580, RHRG7590, RHRG75100

Typical Performance Curves



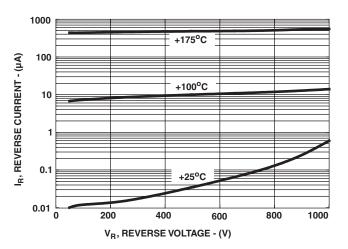
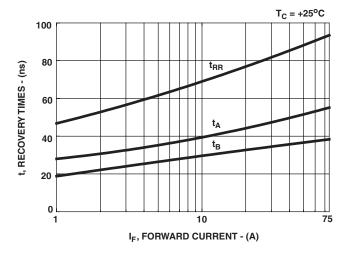


FIGURE 3. TYPICAL FORWARD CURRENT vs. FORWARD VOLTAGE DROP

FIGURE 4. TYPICAL REVERSE CURRENT vs. REVERSE VOLTAGE



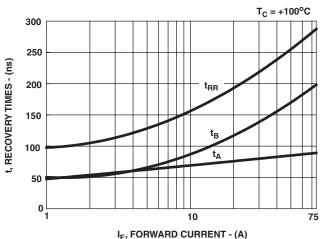
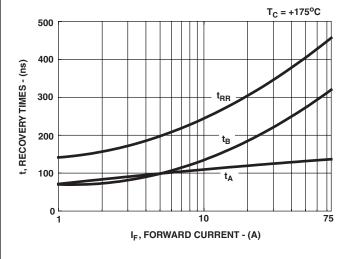


FIGURE 5. TYPICAL t_{RR} , t_{A} AND t_{B} CURVES vs. FORWARD CURRENT AT +25°C

FIGURE 6. TYPICAL t_{RR} , t_{A} AND t_{B} CURVES vs. FORWARD CURRENT AT +100°C



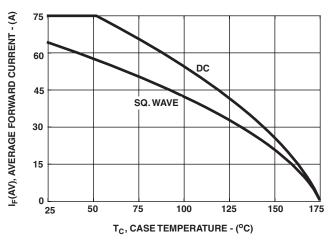


FIGURE 7. TYPICAL t_{RR} , t_{A} AND t_{B} CURVES vs. FORWARD CURRENT AT +175°C

FIGURE 8. CURRENT DERATING CURVE FOR ALL TYPES

Typical Performance Curves (Continued)

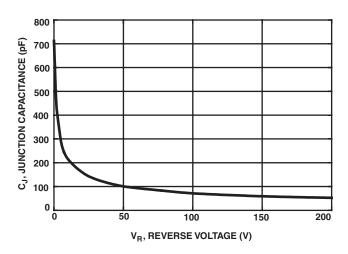
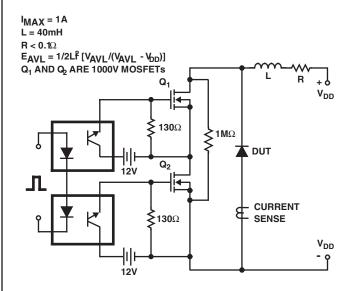


FIGURE 9. TYPICAL JUNCTION CAPACITANCE vs. REVERSE VOLTAGE



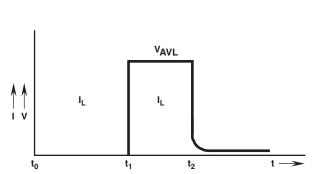


FIGURE 10. AVALANCHE ENERGY TEST CIRCUIT

FIGURE 11. AVALANCHE CURRENT AND VOLTAGE WAVEFORMS

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